

Title (en)

METHOD OF OBTAINING A YELLOW GOLD ALLOY COATING BY ELECTROPLATING WITHOUT THE USE OF TOXIC METALS OR METALLOIDS

Title (de)

VERFAHREN ZUR HERSTELLUNG EINES ÜBERZUGS AUS GELBER GOLDBLEGIERUNG DURCH GALVANISIEREN OHNE VERWENDUNG VON TOXISCHEN METALLEN ODER METALLOIDEN

Title (fr)

PROCÉDÉ D'OBTENTION D'UN DÉPÔT D'ALLIAGE D'OR JAUNE PAR GALVANOPLASTIE SANS UTILISATION DE MÉTAUX OU MÉTALLOÏDES TOXIQUES

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Application

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Abstract (en)

[origin: WO2009037180A1] The invention relates to an electroplated coating in the form of a gold alloy, which has a thickness of between 1 and 800 microns and contains copper. According to the invention, the coating includes indium as third main component. The invention relates to the field of electroplating processes.

IPC 8 full level

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CPC (source: EP US)

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Citation (search report)

See references of WO 2009037180A1

Citation (third parties)

Third party :

JP 2001198693 A 20010724 - ISHIFUKU METAL IND

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